

## APPENDIX

## Changes to Claims:

The following are marked-up versions of the amended claims:

1.     (Amended) A substrate for semiconductor apparatus, comprising:  
a substrate main body having a delineated mounting surface for mounting the semiconductor device;  
a plurality of leads formed on the mounting surface, the plurality of lead radially extending from a peripheral area toward a central area of the substrate main body; and  
a plurality of conduction sections each defining at least part of an external terminal with substantially rectangular contour lines, the conduction sections being electrically connected to the leads.
2.     (Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body comprises a plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, and predetermined ones of the internal surfaces define the conduction sections as the substrate main body is cut along corresponding ones of the through-holes.
3.     (Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body defines a central area and has one through-hole on the side of the central area for each of the leads, and the conduction sections are formed on a surface opposite of a mounting surface of the semiconductor device and are electrically connected to the leads through the through-holes.
4.     (Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body has a plurality of through-holes for each of the leads, and the conduction sections are formed on a surface opposite of the mounting surface of the device and are

electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.

6. (Amended) An electronic apparatus having a circuit substrate mounted with the substrate for semiconductor apparatus according to claim 1.